

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MAGNACHIP SEMICONDUCTOR, LTD.	03/07/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HAECHITECH CORPORATION
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<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15085567
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<b>NAME OF SUBMITTER:</b>	ALICIA M. CHOI
<b>SIGNATURE:</b>	/Alicia M. Choi/
<b>DATE SIGNED:</b>	03/21/2017
<b>Total Attachments: 2</b>	
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## ASSIGNMENT

For valuable consideration,

**MagnaChip Semiconductor, Ltd.**, a Republic of Korea corporation having principal executive offices or place of business at 215, Daesin-ro, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 28429, Republic of Korea (hereinafter called "the Assignor"), hereby assign to:

**Haechitech Corporation**, a Republic of Korea corporation having principal executive offices or place of business at: 525(officetel richiano), 47, Jungsimsangeop-ro Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea; and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of U.S. Patent Applications:

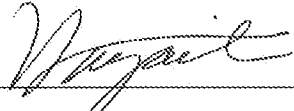
Application No.	Filing Date	Title
14/534,547	11-06-2014	SENSING APPARATUS USING GROUPS OF HALL SENSORS AND APPARATUS USING THE SENSING APPARATUS
14/287,878	05-27-2014	MAGNETIC SENSOR TEST APPARATUS AND METHOD
14/677,553	04-02-2015	CAPACITOR TYPE HUMIDITY SENSOR
15/085,567	03-30-2016	METHOD FOR CONTROLLING OF HALL DEVICE AND MAGNETIC DETECTION APPARATUS USING THE SAME
15/064,837	03-09-2016	PHYSICAL QUANTITY MEASURING APPARATUS AND SIGNAL PROCESSING METHOD THEREOF
15/132,545	04-19-2016	METHOD FOR CALCULATING THE ANGLE OF INCLINATION OF MAGNETIC FIELD IN A SENSOR COORDINATION SYSTEM
15/219,993	07-26-2016	METHOD AND APPARATUS OF CORRECTING OUTPUT VALUE OF GEOMAGNETIC SENSOR

this Assignment includes said applications, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, any reissues, supplemental examinations, and reexaminations, and the right to claim priority based on the filing date of said applications under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and Assignor authorizes the Assignee to apply in all countries in Assignor's name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and

Assignor agrees for itself and its heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, preliminary statements and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

IN TESTIMONY/WITNESS WHEREOF, undersigned Assignor intending to be legally bound, has hereto affixed its signature by its duly authorized representative.

This 9<sup>th</sup> day of March, 2017

  
\_\_\_\_\_  
Signature of Representative

(MagnaChip Semiconductor, Ltd.)

Jae Hee Ha  
\_\_\_\_\_  
Printed Name of Representative

Legal Team Leader  
\_\_\_\_\_  
Title